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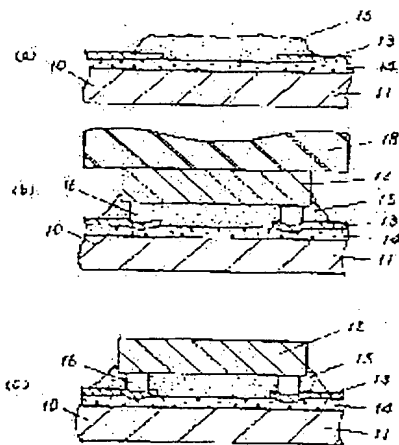
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HATADA KENZO**(54) SEMICONDUCTOR DEVICE****(57)Abstract:**

PURPOSE: To increase reliability under high-temperature surroundings by a method wherein a wiring board on an insulating resin layer of which board wiring is formed is used and the restoration of elasticity of the board wiring and the insulating resin layer is utilized when the board wiring is brought into contact with a bump.

CONSTITUTION: A region in which a semiconductor element 12 is fixed and bonded to a base material 11 of a wiring board 10 is coated with an insulating resin 15 for bonding use so as to include board wiring 13 and an insulating resin layer 14 of the wiring board 10. Then, bumps 16 on the semiconductor element 12 are made to bit in with the board wiring 13; and the semiconductor element 12 is pressurized and pressed to abut on the base material 11 of the wiring board 10. The insulating resin 15 for bonding use is pushed out; and the bumps 16 can electrically be connected to the board wiring 13. Then, the semiconductor element 12 is pressurized; and the insulating resin 15 for bonding use is hardened in a state that the board wiring 13 and the insulating resin layer 14 are deformed. After that, the pressurization operation is released; and the semiconductor element 12 is fixed and bonded to the base material 11 of the wiring board 10.

**LEGAL STATUS**

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